

11/14/03
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Huang, et al.

Serial No.: 09/902,518

Confirmation No.: 7428

Filed: July 10, 2001

For: Method and Apparatus for
Treating Low K Dielectric
Layers to Reduce Diffusion

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Group Art Unit: 2824

Examiner: M. S. Lebentritt

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MAIL STOP 313(C)
Commissioner for Patents
P.O. Box 1450
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Dear Sir:

CERTIFICATE UNDER 37 CFR 1.10

I hereby certify that this correspondence and the documents referred to as attached therein are being deposited on May 8, 2003 with the United States Postal Service in an envelope as "Express Mail Post Office to Addressee," mailing label No. EV349850709US addressed to: Mail Stop 313(c), Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

May 8, 2003
Date

Bm-k 94
Signature

PRELIMINARY AMENDMENT

Prior to examining the above-referenced application, the Applicants request the application be amended as follows.

IN THE SPECIFICATION:

Please replace paragraph [0001] of the specification with the following paragraph:

[0001] This application claims priority to United States provisional patent application serial number 60/218,407, filed July 14, 2000, which is herein incorporated by reference. This application is related to co-pending United States Patent Application No. 09/336,525 (AMAT/3577.X1), filed on June 18, 1999, co-pending United States Patent Application No. 09/657,392 (AMAT/4479), filed on September 8, 2000, and co-